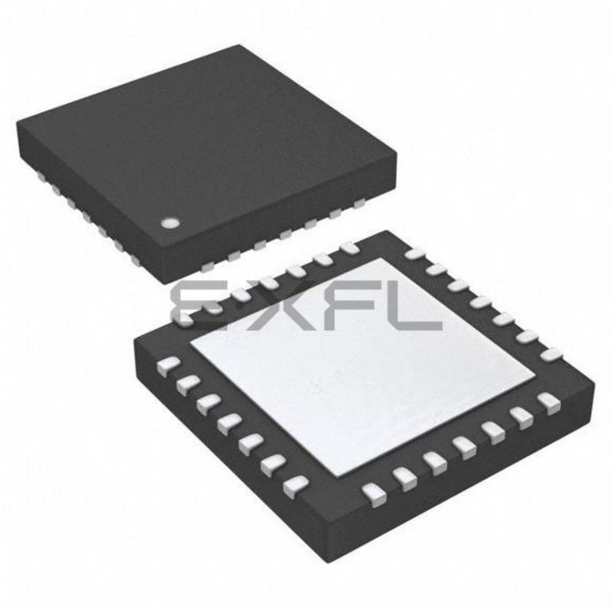

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	16
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf1320t-i-ml

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REGISTER 2-1: OSCTUNE: OSCILLATOR TUNING REGISTER

U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	TUN<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **TUN<5:0>:** Frequency Tuning bits

100000 = Minimum frequency
•
•
•
111111 =
000000 = Oscillator module is running at the factory-calibrated frequency
000001 =
•
•
•
011110 =
011111 = Maximum frequency

2.7 Clock Sources and Oscillator Switching

Like previous PIC18 devices, the PIC18F1220/1320 devices include a feature that allows the system clock source to be switched from the main oscillator to an alternate low-frequency clock source. PIC18F1220/1320 devices offer two alternate clock sources. When enabled, these give additional options for switching to the various power managed operating modes.

Essentially, there are three clock sources for these devices:

- Primary oscillators
- Secondary oscillators
- Internal oscillator block

The **primary oscillators** include the External Crystal and Resonator modes, the External RC modes, the External Clock modes and the internal oscillator block. The particular mode is defined on POR by the contents of Configuration Register 1H. The details of these modes are covered earlier in this chapter.

The **secondary oscillators** are those external sources not connected to the OSC1 or OSC2 pins. These sources may continue to operate even after the controller is placed in a power managed mode.

PIC18F1220/1320 devices offer only the Timer1 oscillator as a secondary oscillator. This oscillator, in all power managed modes, is often the time base for functions such as a real-time clock.

Most often, a 32.768 kHz watch crystal is connected between the RB6/T1OSO and RB7/T1OSI pins. Like the LP mode oscillator circuit, loading capacitors are also connected from each pin to ground. These pins are also used during ICSP operations.

The Timer1 oscillator is discussed in greater detail in **Section 12.2 “Timer1 Oscillator”**.

In addition to being a primary clock source, the **internal oscillator block** is available as a power managed mode clock source. The INTRC source is also used as the clock source for several special features, such as the WDT and Fail-Safe Clock Monitor.

The clock sources for the PIC18F1220/1320 devices are shown in Figure 2-8. See **Section 12.0 “Timer1 Module”** for further details of the Timer1 oscillator. See **Section 19.1 “Configuration Bits”** for Configuration register details.

5.0 MEMORY ORGANIZATION

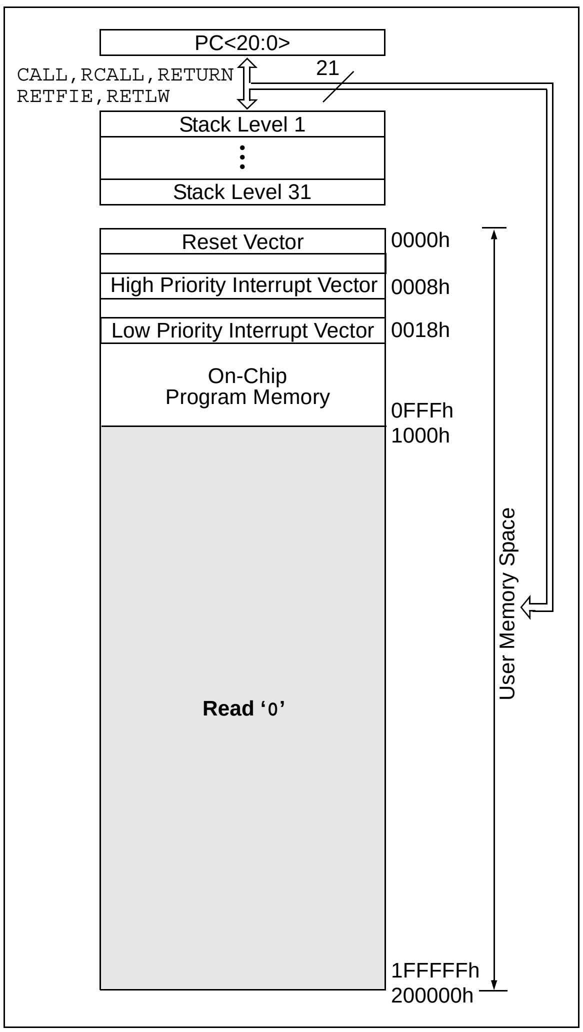
There are three memory types in Enhanced MCU devices. These memory types are:

- Program Memory
- Data RAM
- Data EEPROM

Data and program memory use separate busses, which allows for concurrent access of these types.

Additional detailed information for Flash program memory and data EEPROM is provided in **Section 6.0 "Flash Program Memory"** and **Section 7.0 "Data EEPROM Memory"**, respectively.

FIGURE 5-1: PROGRAM MEMORY MAP AND STACK FOR PIC18F1220



5.1 Program Memory Organization

A 21-bit program counter is capable of addressing the 2-Mbyte program memory space. Accessing a location between the physically implemented memory and the 2-Mbyte address will cause a read of all '0's (a NOP instruction).

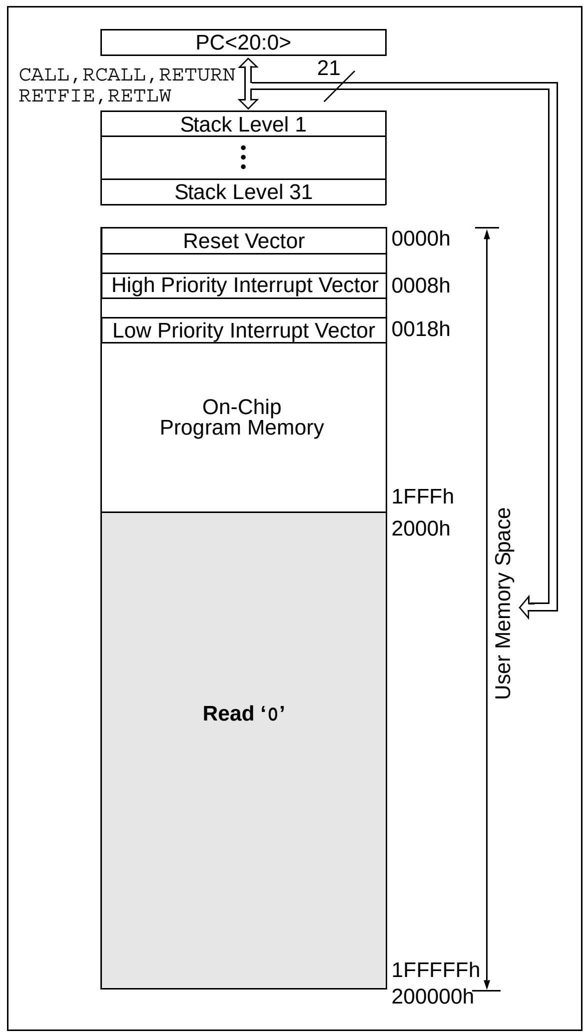
The PIC18F1220 has 4 Kbytes of Flash memory and can store up to 2,048 single-word instructions.

The PIC18F1320 has 8 Kbytes of Flash memory and can store up to 4,096 single-word instructions.

The Reset vector address is at 0000h and the interrupt vector addresses are at 0008h and 0018h.

The program memory maps for the PIC18F1220 and PIC18F1320 devices are shown in Figure 5-1 and Figure 5-2, respectively.

FIGURE 5-2: PROGRAM MEMORY MAP AND STACK FOR PIC18F1320



5.12 Indirect Addressing, INDF and FSR Registers

Indirect addressing is a mode of addressing data memory, where the data memory address in the instruction is not fixed. An FSR register is used as a pointer to the data memory location that is to be read or written. Since this pointer is in RAM, the contents can be modified by the program. This can be useful for data tables in the data memory and for software stacks. Figure 5-8 shows how the fetched instruction is modified prior to being executed.

Indirect addressing is possible by using one of the INDF registers. Any instruction, using the INDF register, actually accesses the register pointed to by the File Select Register, FSR. Reading the INDF register itself, indirectly (FSR = `0`), will read 00h. Writing to the INDF register indirectly, results in a no operation (`NOP`). The FSR register contains a 12-bit address, which is shown in Figure 5-9.

The INDFn register is not a physical register. Addressing INDFn actually addresses the register whose address is contained in the FSRn register (FSRn is a pointer). This is indirect addressing.

Example 5-5 shows a simple use of indirect addressing to clear the RAM in Bank 1 (locations 100h-1FFh) in a minimum number of instructions.

EXAMPLE 5-5: HOW TO CLEAR RAM (BANK 1) USING INDIRECT ADDRESSING

```
        LFSR   FSR0,0x100  ;
NEXT    CLRF   POSTINC0    ; Clear INDF
                           ; register then
                           ; inc pointer
        BTFSS  FSR0H, 1    ; All done with
                           ; Bank1?
        GOTO   NEXT        ; NO, clear next
CONTINUE                   ; YES, continue
```

There are three indirect addressing registers. To address the entire data memory space (4096 bytes), these registers are 12-bit wide. To store the 12 bits of addressing information, two 8-bit registers are required:

1. FSR0: composed of FSR0H:FSR0L
2. FSR1: composed of FSR1H:FSR1L
3. FSR2: composed of FSR2H:FSR2L

In addition, there are registers INDF0, INDF1 and INDF2, which are not physically implemented. Reading or writing to these registers activates indirect addressing, with the value in the corresponding FSR register being the address of the data. If an instruction writes a value to INDF0, the value will be written to the address pointed to by FSR0H:FSR0L. A read from INDF1 reads the data from the address pointed to by FSR1H:FSR1L. INDFn can be used in code anywhere an operand can be used.

If INDF0, INDF1 or INDF2 are read indirectly via an FSR, all '`0`'s are read (zero bit is set). Similarly, if INDF0, INDF1 or INDF2 are written to indirectly, the operation will be equivalent to a `NOP` instruction and the Status bits are not affected.

5.12.1 INDIRECT ADDRESSING OPERATION

Each FSR register has an INDF register associated with it, plus four additional register addresses. Performing an operation using one of these five registers determines how the FSR will be modified during indirect addressing.

When data access is performed using one of the five INDFn locations, the address selected will configure the FSRn register to:

- Do nothing to FSRn after an indirect access (no change) – INDFn
- Auto-decrement FSRn after an indirect access (post-decrement) – POSTDECn
- Auto-increment FSRn after an indirect access (post-increment) – POSTINCn
- Auto-increment FSRn before an indirect access (pre-increment) – PREINCn
- Use the value in the WREG register as an offset to FSRn. Do not modify the value of the WREG or the FSRn register after an indirect access (no change) – PLUSWn

When using the auto-increment or auto-decrement features, the effect on the FSR is not reflected in the Status register. For example, if the indirect address causes the FSR to equal '`0`', the Z bit will not be set.

Auto-incrementing or auto-decrementing an FSR affects all 12 bits. That is, when FSRnL overflows from an increment, FSRnH will be incremented automatically.

Adding these features allows the FSRn to be used as a stack pointer, in addition to its uses for table operations in data memory.

Each FSR has an address associated with it that performs an indexed indirect access. When a data access to this INDFn location (PLUSWn) occurs, the FSRn is configured to add the signed value in the WREG register and the value in FSR to form the address before an indirect access. The FSR value is not changed. The WREG offset range is -128 to +127.

If an FSR register contains a value that points to one of the INDFn, an indirect read will read 00h (zero bit is set), while an indirect write will be equivalent to a `NOP` (Status bits are not affected).

If an indirect addressing write is performed when the target address is an FSRnH or FSRnL register, the data is written to the FSR register, but no pre- or post-increment/decrement is performed.

EXAMPLE 6-3: WRITING TO FLASH PROGRAM MEMORY (CONTINUED)

```
WRITE_WORD_TO_HREGS
           MOVF    POSTINC0, W             ; get low byte of buffer data and increment FSR0
           MOVWF   TABLAT                  ; present data to table latch
           TBLWT+*                         ; short write
                                           ; to internal TBLWT holding register, increment
                                             TBLPTR
           DECFSZ  COUNTER                 ; loop until buffers are full
           GOTO    WRITE_WORD_TO_HREGS
PROGRAM_MEMORY
           BCF     INTCON, GIE             ; disable interrupts
           MOVLW   55h                     ; required sequence
           MOVWF   EECON2                  ; write 55H
           MOVLW   AAh
           MOVWF   EECON2                  ; write AAH
           BSF     EECON1, WR              ; start program (CPU stall)
           NOP
           BSF     INTCON, GIE             ; re-enable interrupts
           DECFSZ  COUNTER_HI              ; loop until done
           GOTO PROGRAM_LOOP
           BCF     EECON1, WREN            ; disable write to memory
```

6.5.2 WRITE VERIFY

Depending on the application, good programming practice may dictate that the value written to the memory should be verified against the original value. This should be used in applications where excessive writes can stress bits near the specification limit.

6.5.3 UNEXPECTED TERMINATION OF WRITE OPERATION

If a write is terminated by an unplanned event, such as loss of power or an unexpected Reset, the memory location just programmed should be verified and reprogrammed if needed. The WRERR bit is set when a write operation is interrupted by a $\overline{\text{MCLR}}$ Reset, or a WDT Time-out Reset during normal operation. In these situations, users can check the WRERR bit and rewrite the location.

6.6 Flash Program Operation During Code Protection

See **Section 19.0 “Special Features of the CPU”** for details on code protection of Flash program memory.

TABLE 6-2: REGISTERS ASSOCIATED WITH PROGRAM FLASH MEMORY

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
TBLPTRU	—	—	bit 21	Program Memory Table Pointer Upper Byte (TBLPTR<20:16>)					--00 0000	--00 0000
TBPLTRH	Program Memory Table Pointer High Byte (TBLPTR<15:8>)								0000 0000	0000 0000
TBLPTRL	Program Memory Table Pointer High Byte (TBLPTR<7:0>)								0000 0000	0000 0000
TABLAT	Program Memory Table Latch								0000 0000	0000 0000
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBIF	0000 000x	0000 000u
EECON2	EEPROM Control Register 2 (not a physical register)								—	—
EECON1	EEPGD	CFGS	—	FREE	WRERR	WREN	WR	RD	xx-0 x000	uu-0 u000
IPR2	OSCFIP	—	—	EEIP	—	LVDIP	TMR3IP	—	1--1 -11-	1--1 -11-
PIR2	OSCFIF	—	—	EEIF	—	LVDIF	TMR3IF	—	0--0 -00-	0--0 -00-
PIE2	OSCFIE	—	—	EEIE	—	LVDIE	TMR3IE	—	0--0 -00-	0--0 -00-

Legend: x = unknown, u = unchanged, – = unimplemented, read as ‘0’.
Shaded cells are not used during Flash/EEPROM access.

TABLE 16-3: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.00	33332	0.300	0.00	16665	0.300	0.00	8332	300	-0.01	6665
1.2	1.200	0.00	8332	1.200	0.02	4165	1.200	0.02	2082	1200	-0.04	1665
2.4	2.400	0.02	4165	2.400	0.02	2082	2.402	0.06	1040	2400	-0.04	832
9.6	9.606	0.06	1040	9.596	-0.03	520	9.615	0.16	259	9615	-0.16	207
19.2	19.193	-0.03	520	19.231	0.16	259	19.231	0.16	129	19230	-0.16	103
57.6	57.803	0.35	172	57.471	-0.22	86	58.140	0.94	42	57142	0.79	34
115.2	114.943	-0.22	86	116.279	0.94	42	113.636	-1.36	21	117647	-2.12	16

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.01	3332	300	-0.04	1665	300	-0.04	832
1.2	1.200	0.04	832	1201	-0.16	415	1201	-0.16	207
2.4	2.404	0.16	415	2403	-0.16	207	2403	-0.16	103
9.6	9.615	0.16	103	9615	-0.16	51	9615	-0.16	25
19.2	19.231	0.16	51	19230	-0.16	25	19230	-0.16	12
57.6	58.824	2.12	16	55555	3.55	8	—	—	—
115.2	111.111	-3.55	8	—	—	—	—	—	—

16.3.4 AUTO-WAKE-UP ON SYNC BREAK CHARACTER

During Sleep mode, all clocks to the EUSART are suspended. Because of this, the Baud Rate Generator is inactive and a proper byte reception cannot be performed. The auto-wake-up feature allows the controller to wake-up due to activity on the RX/DT line while the EUSART is operating in Asynchronous mode.

The auto-wake-up feature is enabled by setting the WUE bit (BAUDCTL<1>). Once set, the typical receive sequence on RX/DT is disabled and the EUSART remains in an Idle state, monitoring for a wake-up event independent of the CPU mode. A wake-up event consists of a high-to-low transition on the RX/DT line. (This coincides with the start of a Sync Break or a Wake-up Signal character for the LIN protocol.)

Following a wake-up event, the module generates an RCIF interrupt. The interrupt is generated synchronously to the Q clocks in normal operating modes (Figure 16-7) and asynchronously if the device is in Sleep mode (Figure 16-8). The interrupt condition is cleared by reading the RCREG register.

The WUE bit is automatically cleared once a low-to-high transition is observed on the RX line, following the wake-up event. At this point, the EUSART module is in Idle mode and returns to normal operation. This signals to the user that the Sync Break event is over.

16.3.4.1 Special Considerations Using Auto-Wake-up

Since auto-wake-up functions by sensing rising edge transitions on RX/DT, information with any state changes before the Stop bit may signal a false end-of-character and cause data or framing errors. To work properly, therefore, the initial character in the transmission must be all '0's. This can be 00h (8 bytes) for standard RS-232 devices, or 000h (12 bits) for LIN bus.

Oscillator start-up time must also be considered, especially in applications using oscillators with longer start-up intervals (i.e., LP, XT or HS/PLL mode). The Sync Break (or Wake-up Signal) character must be of sufficient length and be followed by a sufficient period, to allow enough time for the selected oscillator to start and provide proper initialization of the EUSART.

16.3.4.2 Special Considerations Using the WUE Bit

The timing of WUE and RCIF events may cause some confusion when it comes to determining the validity of received data. As noted, setting the WUE bit places the EUSART in an Idle mode. The wake-up event causes a receive interrupt by setting the RCIF bit. The WUE bit is cleared after this when a rising edge is seen on RX/DT. The interrupt condition is then cleared by reading the RCREG register. Ordinarily, the data in RCREG will be dummy data and should be discarded.

The fact that the WUE bit has been cleared (or is still set) and the RCIF flag is set should not be used as an indicator of the integrity of the data in RCREG. Users should consider implementing a parallel method in firmware to verify received data integrity.

To assure that no actual data is lost, check the RCIDL bit to verify that a receive operation is not in process. If a receive operation is not occurring, the WUE bit may then be set just prior to entering the Sleep mode.

FIGURE 16-7: AUTO-WAKE-UP BIT (WUE) TIMINGS DURING NORMAL OPERATION

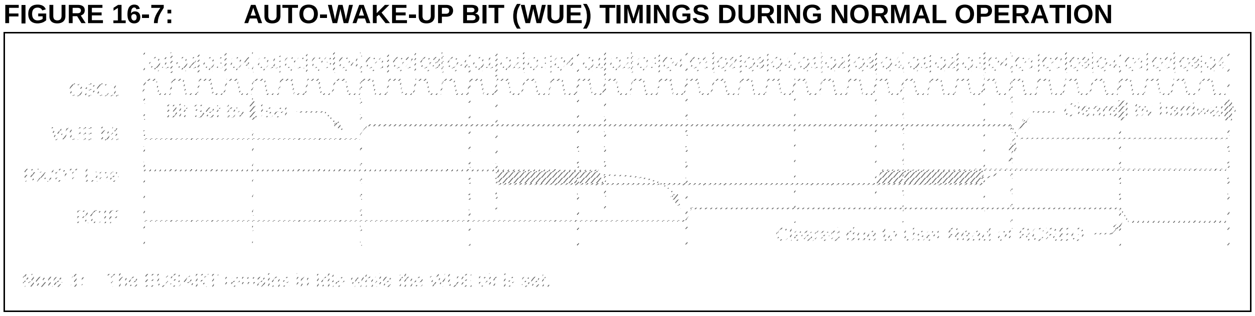
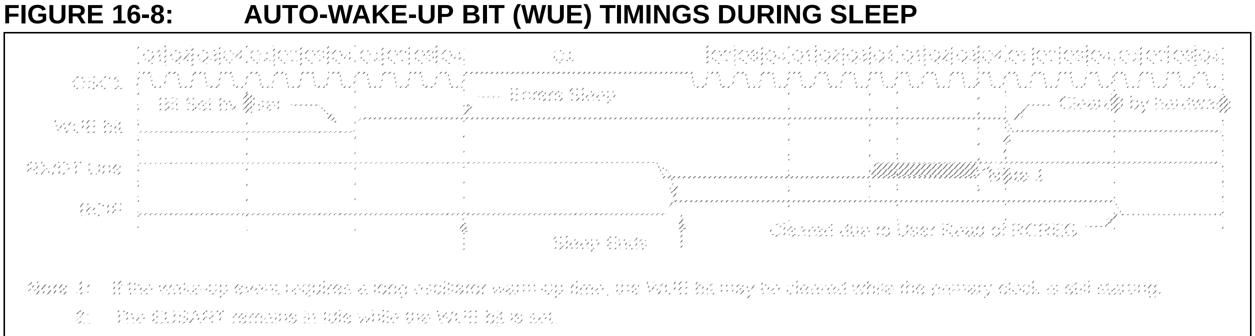


FIGURE 16-8: AUTO-WAKE-UP BIT (WUE) TIMINGS DURING SLEEP



The analog reference voltage is software selectable to either the device's positive and negative supply voltage (AVDD and AVSS), or the voltage level on the RA3/AN3/VREF+ and RA2/AN2/VREF- pins.

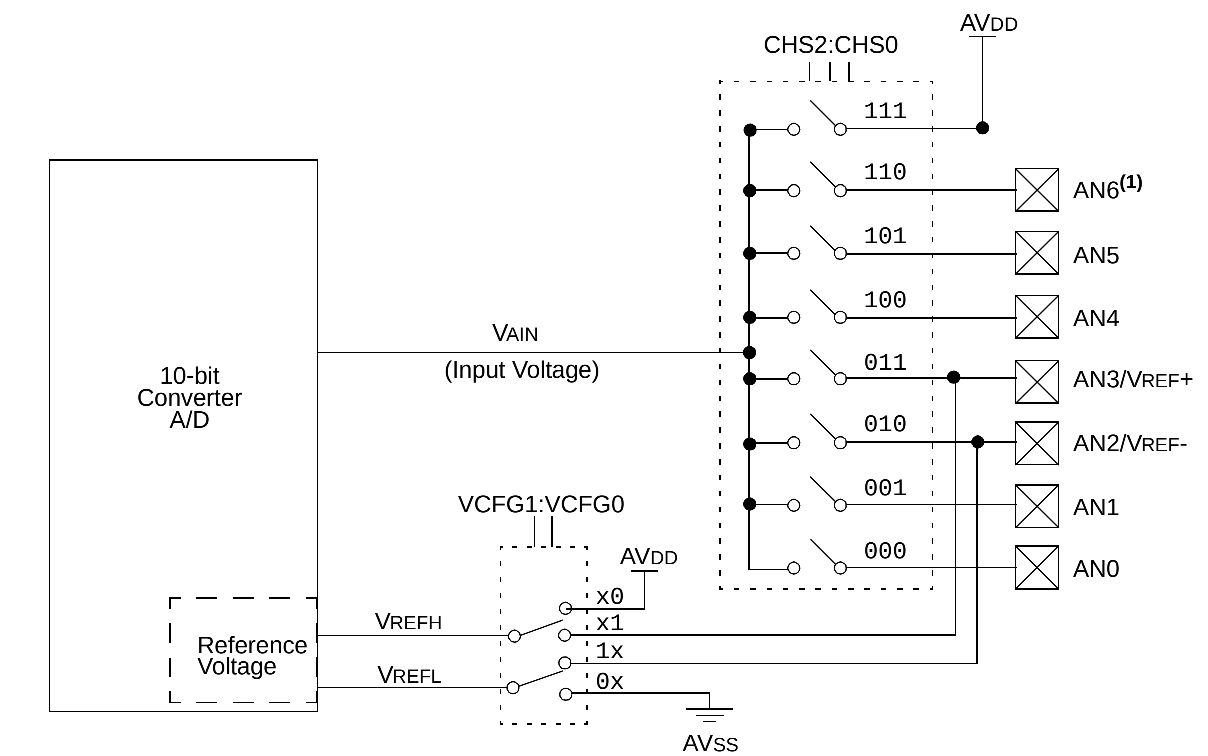
The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The output of the sample and hold is the input into the converter, which generates the result via successive approximation.

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D converter can be configured as an analog input, or as a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH/ADRESL registers, the GO/DONE bit (ADCON0 register) is cleared and A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 17-1.

FIGURE 17-1: A/D BLOCK DIAGRAM



Note 1: I/O pins have diode protection to VDD and VSS.

19.5.2 DATA EEPROM CODE PROTECTION

The entire data EEPROM is protected from external reads and writes by two bits: CPD and WRTD. CPD inhibits external reads and writes of data EEPROM. WRTD inhibits external writes to data EEPROM. The CPU can continue to read and write data EEPROM, regardless of the protection bit settings.

19.5.3 CONFIGURATION REGISTER PROTECTION

The Configuration registers can be write-protected. The WRTC bit controls protection of the Configuration registers. In normal execution mode, the WRTC bit is readable only. WRTC can only be written via ICSP or an external programmer.

19.6 ID Locations

Eight memory locations (200000h-200007h) are designated as ID locations, where the user can store checksum or other code identification numbers. These locations are both readable and writable during normal execution through the TBLRD and TBLWT instructions, or during program/verify. The ID locations can be read when the device is code-protected.

19.7 In-Circuit Serial Programming

PIC18F1220/1320 microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed (see Table 19-4).

Note:	The Timer1 oscillator shares the T1OSI and T1OSO pins with the PGD and PGC pins used for programming and debugging. When using the Timer1 oscillator, In-Circuit Serial Programming (ICSP) may not function correctly (high voltage or low voltage), or the In-Circuit Debugger (ICD) may not communicate with the controller. As a result of using either ICSP or ICD, the Timer1 crystal may be damaged. If ICSP or ICD operations are required, the crystal should be disconnected from the circuit (disconnect either lead), or installed after programming. The oscillator loading capacitors may remain in-circuit during ICSP or ICD operation.

TABLE 19-4: ICSP/ICD CONNECTIONS

Signal	Pin	Notes
PGD	RB7/PGD/T1OSI/P1D/KBI3	Shared with T1OSC – protect crystal
PGC	RB6/PGC/T1OSO/T13CKI/P1C/KBI2	Shared with T1OSC – protect crystal
$\overline{MCLR}$	$\overline{MCLR}$/VPP/RA5	
VDD	VDD	
VSS	VSS	
PGM	RB5/PGM/KBI1	Optional – pull RB5 low is LVP enabled

19.8 In-Circuit Debugger

When the DEBUG bit in Configuration register, CONFIG4L, is programmed to a '0', the In-Circuit Debugger functionality is enabled. This function allows simple debugging functions when used with MPLAB® IDE. When the microcontroller has this feature enabled, some resources are not available for general use. Table 19-5 shows which resources are required by the background debugger.

TABLE 19-5: DEBUGGER RESOURCES

I/O pins:	RB6, RB7
Stack:	2 levels
Program Memory:	512 bytes
Data Memory:	10 bytes

To use the In-Circuit Debugger function of the microcontroller, the design must implement In-Circuit Serial Programming connections to $\overline{MCLR}$/VPP, VDD, VSS, RB7 and RB6. This will interface to the In-Circuit Debugger module available from Microchip, or one of the third party development tool companies (see the note following **Section 19.7 "In-Circuit Serial Programming"** for more information).

CLRF	Clear f
Syntax:	[*label*] CLRF f [,a]
Operands:	$0 \le f \le 255$ $a \in [0,1]$
Operation:	000h → f 1 → Z
Status Affected:	Z
Encoding:	`0110` `101a` `ffff` `ffff`
Description:	Clears the contents of the specified register. If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: `CLRF FLAG_REG`

Before Instruction
FLAG_REG = 0x5A

After Instruction
FLAG_REG = 0x00

CLRWDT	Clear Watchdog Timer
Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	000h → WDT, 000h → WDT postscaler, 1 → $\overline{TO}$, 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Encoding:	`0000` `0000` `0000` `0100`
Description:	`CLRWDT` instruction resets the Watchdog Timer. It also resets the postscaler of the WDT. Status bits, $\overline{TO}$ and $\overline{PD}$, are set.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	Process Data	No operation

Example: `CLRWDT`

Before Instruction
WDT Counter = ?

After Instruction
WDT Counter = 0x00
WDT Postscaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

DAW — Decimal Adjust W Register

Syntax: [*label*] DAW

Operands: None

Operation:
If [W<3:0> > 9] or [DC = 1] then
(W<3:0>) + 6 → W<3:0>;
else
(W<3:0>) → W<3:0>;

If [W<7:4> > 9] or [C = 1] then
(W<7:4>) + 6 → W<7:4>;
else
(W<7:4>) → W<7:4>;

Status Affected: C, DC

Encoding:

0000	0000	0000	0111

Description: `DAW` adjusts the 8-bit value in W, resulting from the earlier addition of two variables (each in packed BCD format) and produces a correct packed BCD result. The Carry bit may be set by `DAW` regardless of its setting prior to the `DAW` instruction.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register W	Process Data	Write W

Example 1: `DAW`

Before Instruction
W = 0xA5
C = 0
DC = 0

After Instruction
W = 0x05
C = 1
DC = 0

Example 2:

Before Instruction
W = 0xCE
C = 0
DC = 0

After Instruction
W = 0x34
C = 1
DC = 0

DECF — Decrement f

Syntax: [*label*] DECF f [,d [,a]]

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]
a ∈ [0,1]

Operation: (f) – 1 → dest

Status Affected: C, DC, N, OV, Z

Encoding:

0000	01da	ffff	ffff

Description: Decrement register ‘f’. If ‘d’ is ‘0’, the result is stored in W. If ‘d’ is ‘1’, the result is stored back in register ‘f’ (default). If ‘a’ is ‘0’, the Access Bank will be selected, overriding the BSR value. If ‘a’ = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination

Example: `DECF CNT`

Before Instruction
CNT = 0x01
Z = 0

After Instruction
CNT = 0x00
Z = 1

INCFSZ	Increment f, skip if 0
Syntax:	[*label*] INCFSZ f [,d [,a]]
Operands:	0 ≤ f ≤ 255 d ∈ [0,1] a ∈ [0,1]
Operation:	(f) + 1 → dest, skip if result = 0
Status Affected:	None
Encoding:	0011 11da ffff ffff
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default). If the result is '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a 2-cycle instruction. If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).
Words:	1
Cycles:	1(2) **Note:** 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:

```
HERE    INCFSZ  CNT
NZERO   :
ZERO    :
```

Before Instruction

PC = Address (HERE)

After Instruction

CNT = CNT + 1
If CNT = 0;
PC = Address (ZERO)
If CNT ≠ 0;
PC = Address (NZERO)

INFSNZ	Increment f, skip if not 0
Syntax:	[*label*] INFSNZ f [,d [,a]]
Operands:	0 ≤ f ≤ 255 d ∈ [0,1] a ∈ [0,1]
Operation:	(f) + 1 → dest, skip if result ≠ 0
Status Affected:	None
Encoding:	0100 10da ffff ffff
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default). If the result is not '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a 2-cycle instruction. If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).
Words:	1
Cycles:	1(2) **Note:** 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:

```
HERE    INFSNZ REG
ZERO
NZERO
```

Before Instruction

PC = Address (HERE)

After Instruction

REG = REG + 1
If REG ≠ 0;
PC = Address (NZERO)
If REG = 0;
PC = Address (ZERO)

NEGF	**Negate f**
Syntax:	[*label*] NEGF f [,a]
Operands:	0 ≤ f ≤ 255 a ∈ [0,1]
Operation:	$(\bar{f}) + 1 \rightarrow f$
Status Affected:	N, OV, C, DC, Z
Encoding:	`0110` `110a` `ffff` `ffff`
Description:	Location ‘f’ is negated using two’s complement. The result is placed in the data memory location ‘f’. If ‘a’ is ‘0’, the Access Bank will be selected, overriding the BSR value. If ‘a’ = 1, then the bank will be selected as per the BSR value.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write register ‘f’

Example: `NEGF REG, 1`

Before Instruction
REG = 0011 1010 [0x3A]

After Instruction
REG = 1100 0110 [0xC6]

NOP	**No Operation**
Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Encoding:	`0000` `0000` `0000` `0000` `1111` `xxxx` `xxxx` `xxxx`
Description:	No operation.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	No operation	No operation

Example:

None.

22.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

Ambient temperature under bias....................-40°C to +125°C
Storage temperature .... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$ and RA4).................... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} .... -0.3V to +5.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** .... 0V to +13.25V
Voltage on RA4 with respect to Vss .... 0V to +8.5V
Total power dissipation **(Note 1)**....................1.0W
Maximum current out of V_{SS} pin ....300 mA
Maximum current into V_{DD} pin ....250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD})....................±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ....±20 mA
Maximum output current sunk by any I/O pin....................25 mA
Maximum output current sourced by any I/O pin....................25 mA
Maximum current sunk by all ports....................200 mA
Maximum current sourced by all ports ....200 mA

Note 1: Power dissipation is calculated as follows:
$Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{MCLR}/V_{PP}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}/V_{PP}$ pin, rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 22-2: LOW-VOLTAGE DETECT CHARACTERISTICS (CONTINUED)

PIC18LF1220/1320 (Industrial)				**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC18F1220/1320 (Industrial, Extended)				**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**		**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D420F		LVD Voltage on VDD Transition High-to-Low		Industrial Low Voltage **(-40°C to -10°C)**				
		PIC18LF1220/1320	LVDL<3:0> = 0000	N/A	N/A	N/A	V	Reserved
			LVDL<3:0> = 0001	N/A	N/A	N/A	V	Reserved
			LVDL<3:0> = 0010	1.99	2.26	2.53	V	
			LVDL<3:0> = 0011	2.16	2.45	2.75	V	
			LVDL<3:0> = 0100	2.25	2.55	2.86	V	
			LVDL<3:0> = 0101	2.43	2.77	3.10	V	
			LVDL<3:0> = 0110	2.53	2.87	3.21	V	
			LVDL<3:0> = 0111	2.70	3.07	3.43	V	
			LVDL<3:0> = 1000	2.96	3.36	3.77	V	
			LVDL<3:0> = 1001	3.14	3.57	4.00	V	
			LVDL<3:0> = 1010	3.23	3.67	4.11	V	
			LVDL<3:0> = 1011	3.41	3.87	4.34	V	
			LVDL<3:0> = 1100	3.58	4.07	4.56	V	
			LVDL<3:0> = 1101	3.76	4.28	4.79	V	
			LVDL<3:0> = 1110	4.04	4.60	5.15	V	
		LVD Voltage on VDD Transition High-to-Low		Industrial **(-10°C to +85°C)**				
D420G		PIC18F1220/1320	LVDL<3:0> = 1101	3.93	4.28	4.62	V	
			LVDL<3:0> = 1110	4.23	4.60	4.96	V	
		LVD Voltage on VDD Transition High-to-Low		Industrial **(-40°C to -10°C)**				
D420H		PIC18F1220/1320	LVDL<3:0> = 1101	3.76	4.28	4.79	V	
			LVDL<3:0> = 1110	4.04	4.60	5.15	V	
		LVD Voltage on VDD Transition High-to-Low		Extended **(-10°C to +85°C)**				
D420J		PIC18F1220/1320	LVDL<3:0> = 1101	3.94	4.28	4.62	V	
			LVDL<3:0> = 1110	4.23	4.60	4.96	V	
		LVD Voltage on VDD Transition High-to-Low		Extended **(-40°C to -10°C, +85°C to +125°C)**				
D420K		PIC18F1220/1320	LVDL<3:0> = 1101	3.77	4.28	4.79	V	
			LVDL<3:0> = 1110	4.05	4.60	5.15	V	

Legend: Shading of rows is to assist in readability of the table.

† Production tested at TAMB = 25°C. Specifications over temperature limits ensured by characterization.

22.4 AC (Timing) Characteristics

22.4.1 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS		3. TCC:ST	(I^2C specifications only)
2. TppS		4. Ts	(I^2C specifications only)
T			
F	Frequency	T	Time
Lowercase letters (pp) and their meanings:			
pp			
cc	CCP1	osc	OSC1
ck	CLKO	rd	$\overline{\text{RD}}$
cs	$\overline{\text{CS}}$	rw	$\overline{\text{RD}}$ or $\overline{\text{WR}}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{\text{SS}}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T13CKI
mc	$\overline{\text{MCLR}}$	wr	$\overline{\text{WR}}$
Uppercase letters and their meanings:			
S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-Impedance)	V	Valid
L	Low	Z	High-Impedance
I^2C only			
AA	output access	High	High
BUF	Bus free	Low	Low
TCC:ST (I^2C specifications only)			
CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	Stop condition
STA	Start condition		

FIGURE 23-11: TYPICAL IDD vs. FOSC OVER VDD PRI_IDLE, EC MODE, +25°C

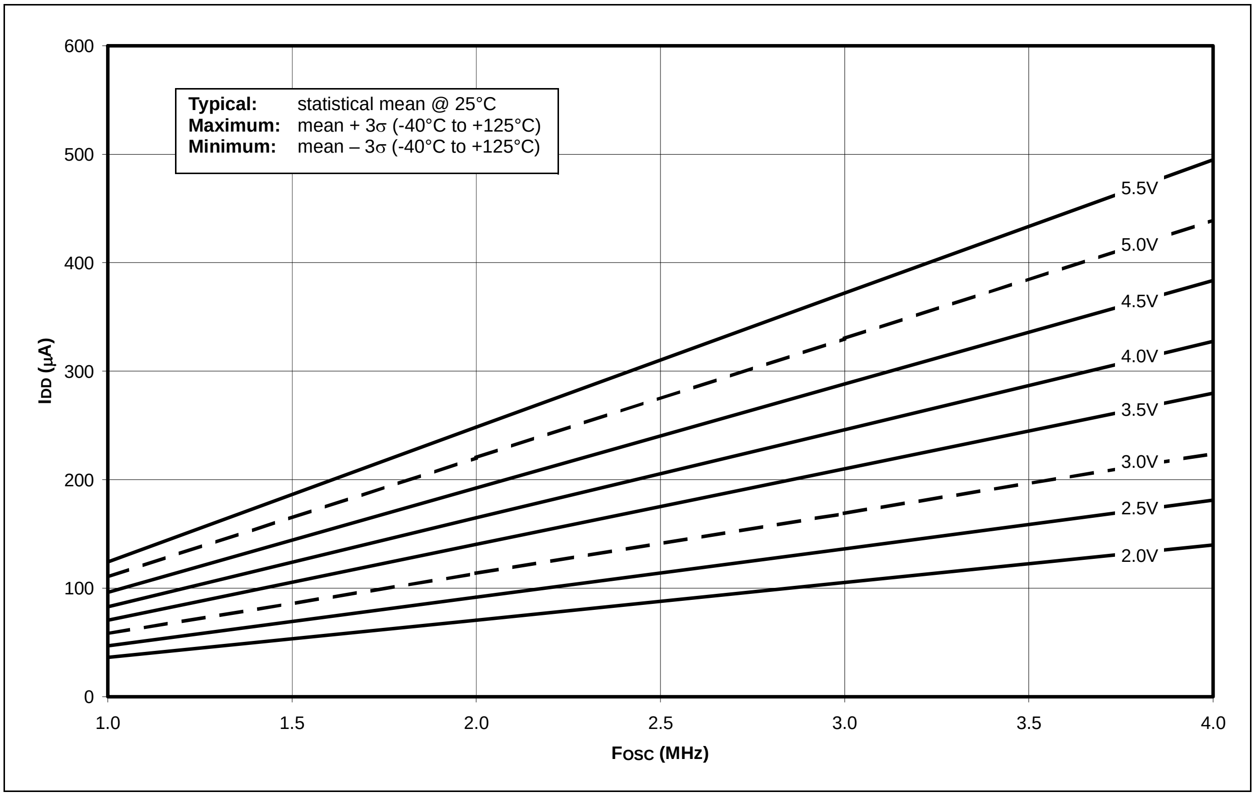


FIGURE 23-12: MAXIMUM IDD vs. FOSC OVER VDD PRI_IDLE, EC MODE, -40°C TO +125°C

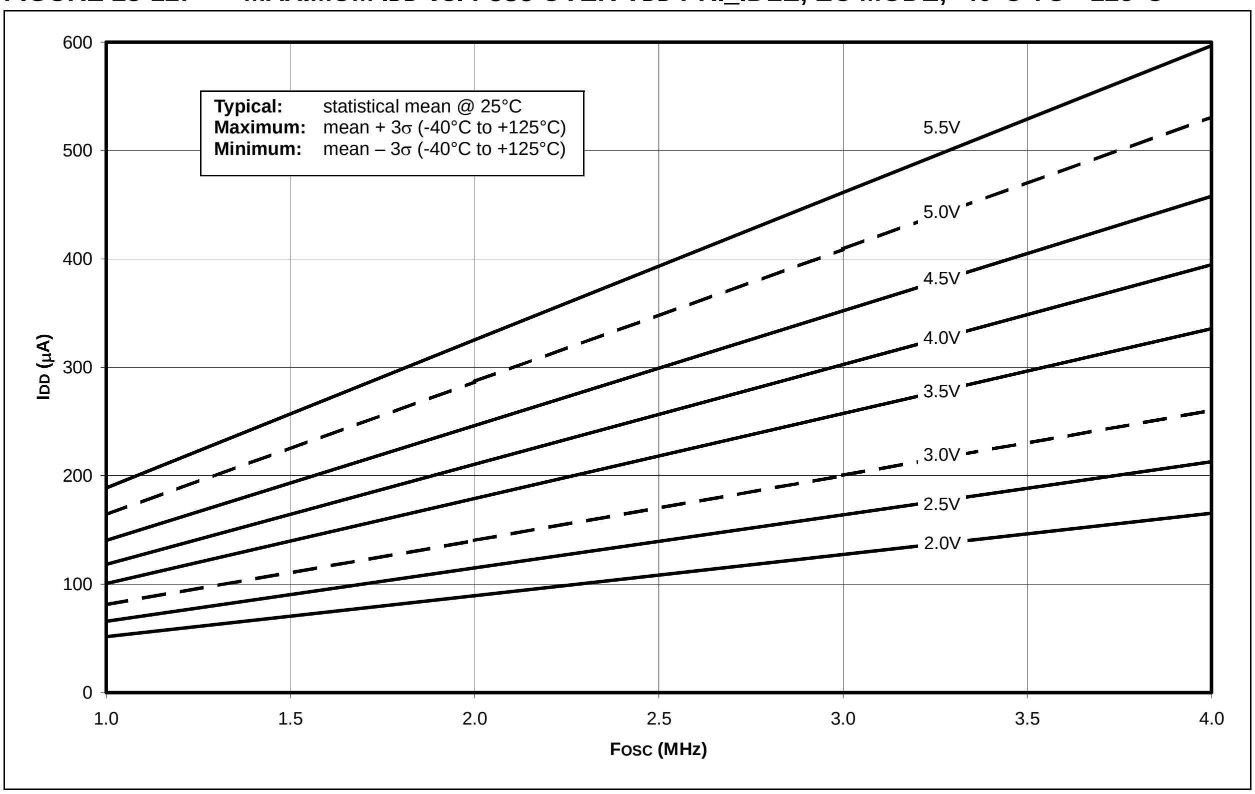


FIGURE 23-29: ΔIPD FSCM vs. VDD OVER TEMPERATURE PRI_IDLE MODE, EC OSCILLATOR AT 32 kHz, -40°C TO +125°C

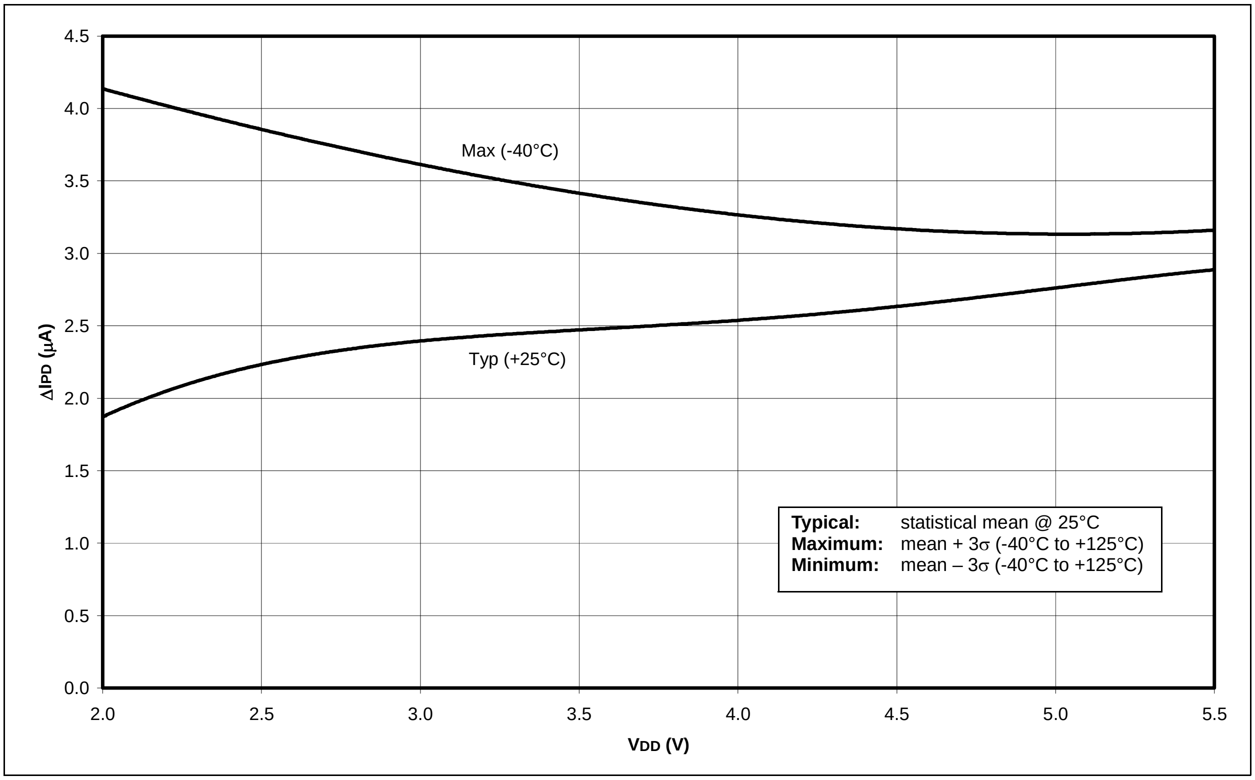
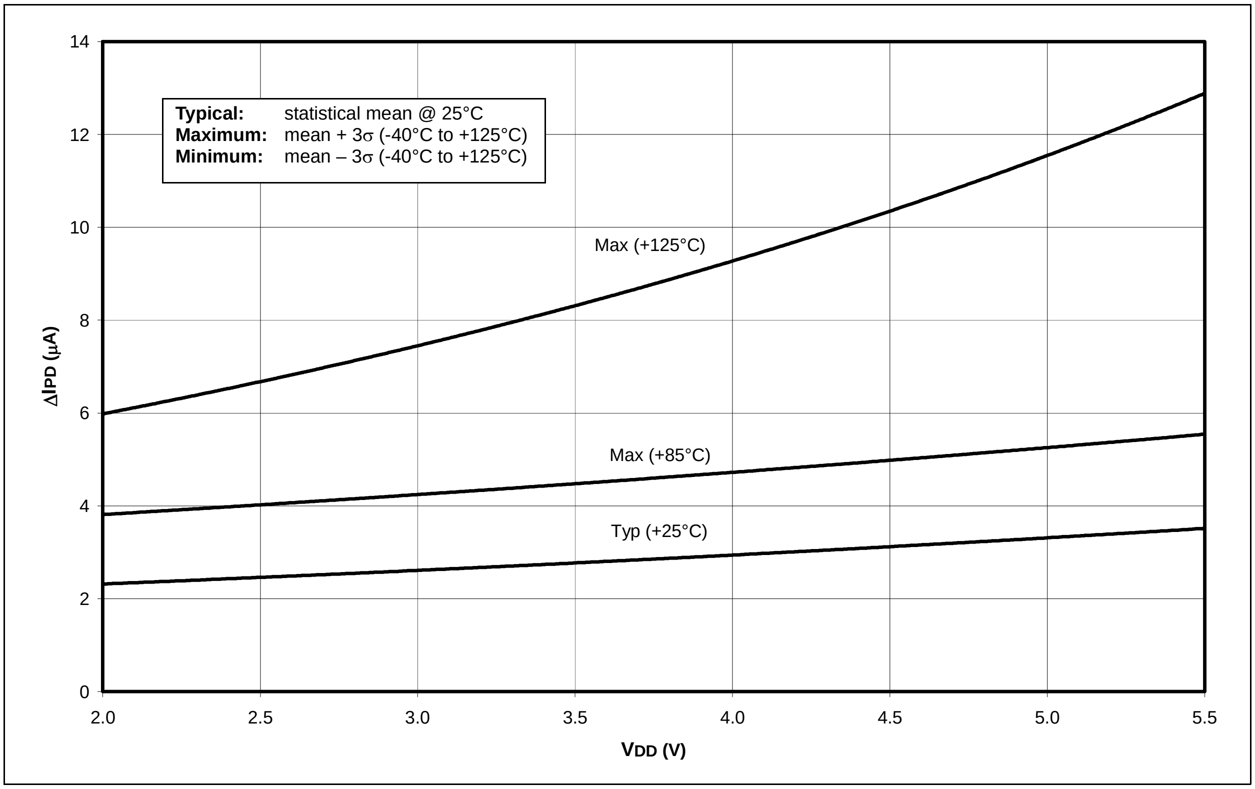


FIGURE 23-30: ΔIPD WDT, -40°C TO +125°C SLEEP MODE, ALL PERIPHERALS DISABLED



APPENDIX A: REVISION HISTORY

Revision A (August 2002)

Original data sheet for PIC18F1220/1320 devices.

Revision B (November 2002)

This revision includes significant changes to **Section 2.0**, **Section 3.0** and **Section 19.0**, as well as updates to the Electrical Specifications in **Section 22.0** and includes minor corrections to the data sheet text.

Revision C (May 2004)

This revision includes updates to the Electrical Specifications in **Section 22.0**, the DC and AC Characteristics Graphs and Tables in **Section 23.0** and includes minor corrections to the data sheet text.

Revision D (October 2006)

This revision includes updates to the packaging diagrams.

Revision E (January 2007)

This revision includes updates to the packaging diagrams.

Revision F (February 2007)

This revision includes updates to the packaging diagrams.

Revision G (April 2015)

Added Section 22.5: High Temperature Operation in the Electrical Specifications section.

APPENDIX B: DEVICE DIFFERENCES

The differences between the devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Features	PIC18F1220	PIC18F1320
Program Memory (Bytes)	4096	8192
Program Memory (Instructions)	2048	4096
Interrupt Sources	15	15
I/O Ports	Ports A, B	Ports A, B
Enhanced Capture/Compare/PWM Modules	1	1
10-bit Analog-to-Digital Module	7 input channels	7 input channels
Packages	18-pin SDIP 18-pin SOIC 20-pin SSOP 28-pin QFN	18-pin SDIP 18-pin SOIC 20-pin SSOP 28-pin QFN

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